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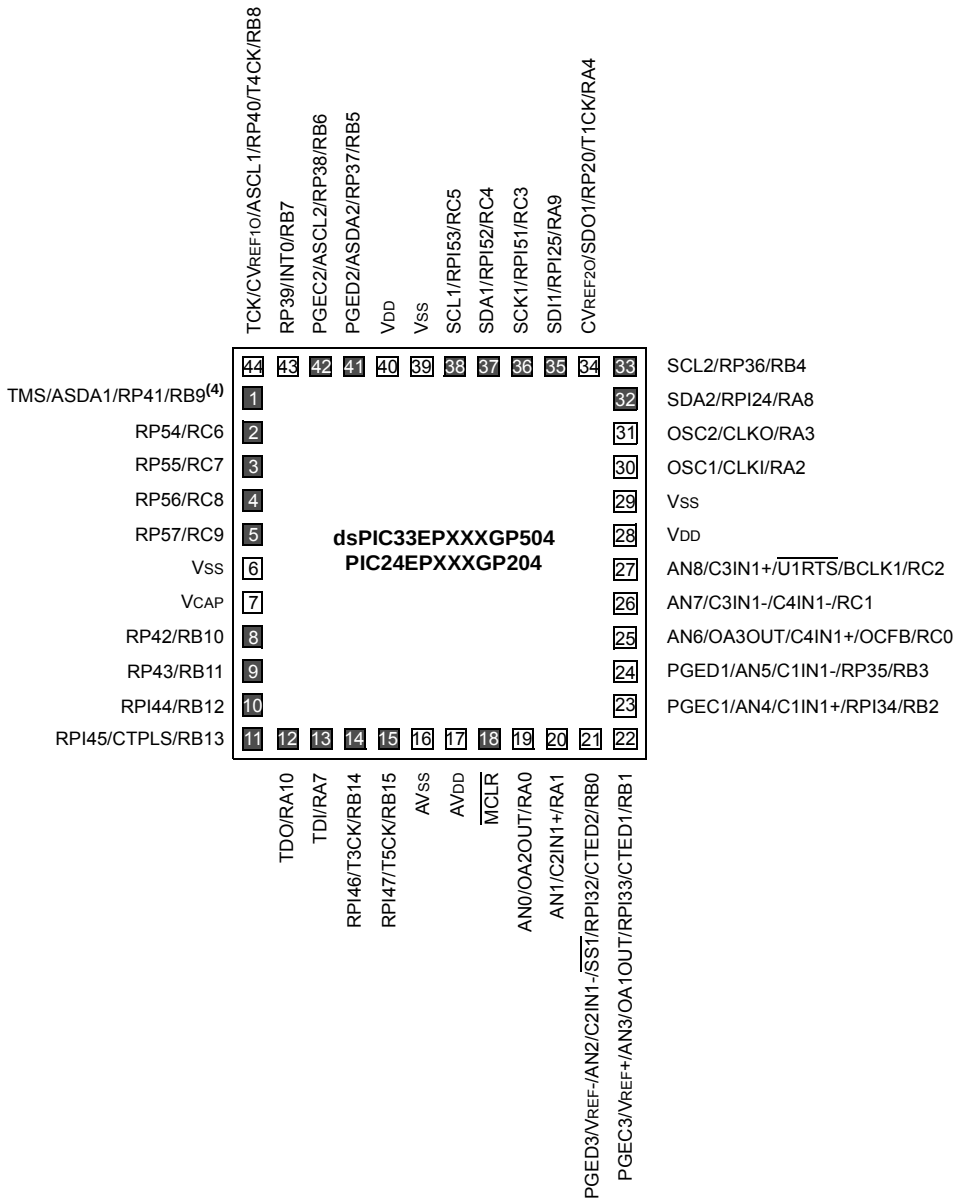
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	32KB (10.7K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep32mc202t-i-ss

Pin Diagrams (Continued)

44-Pin VTLA(1,2,3)

■ = Pins are up to 5V tolerant



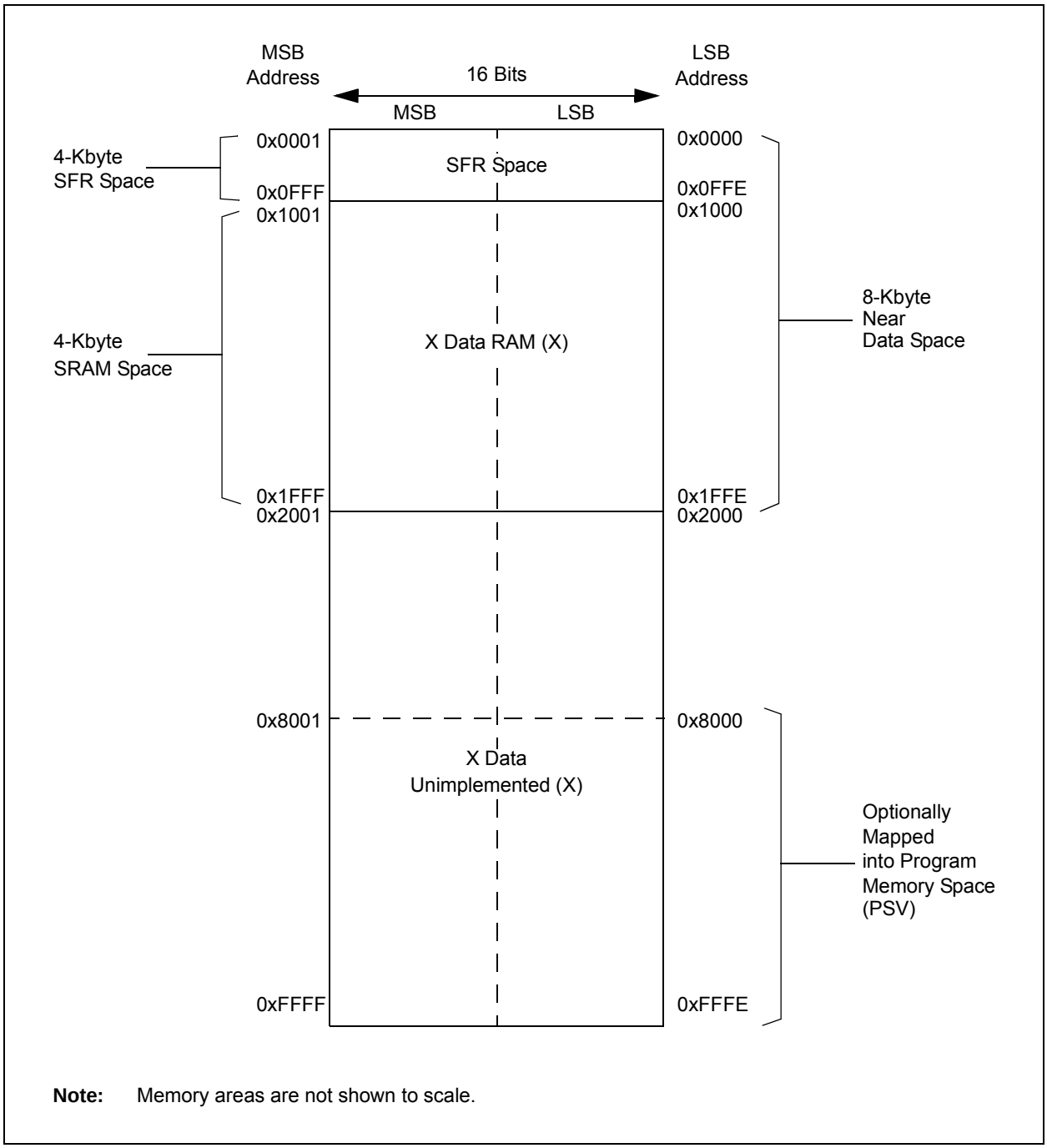
Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

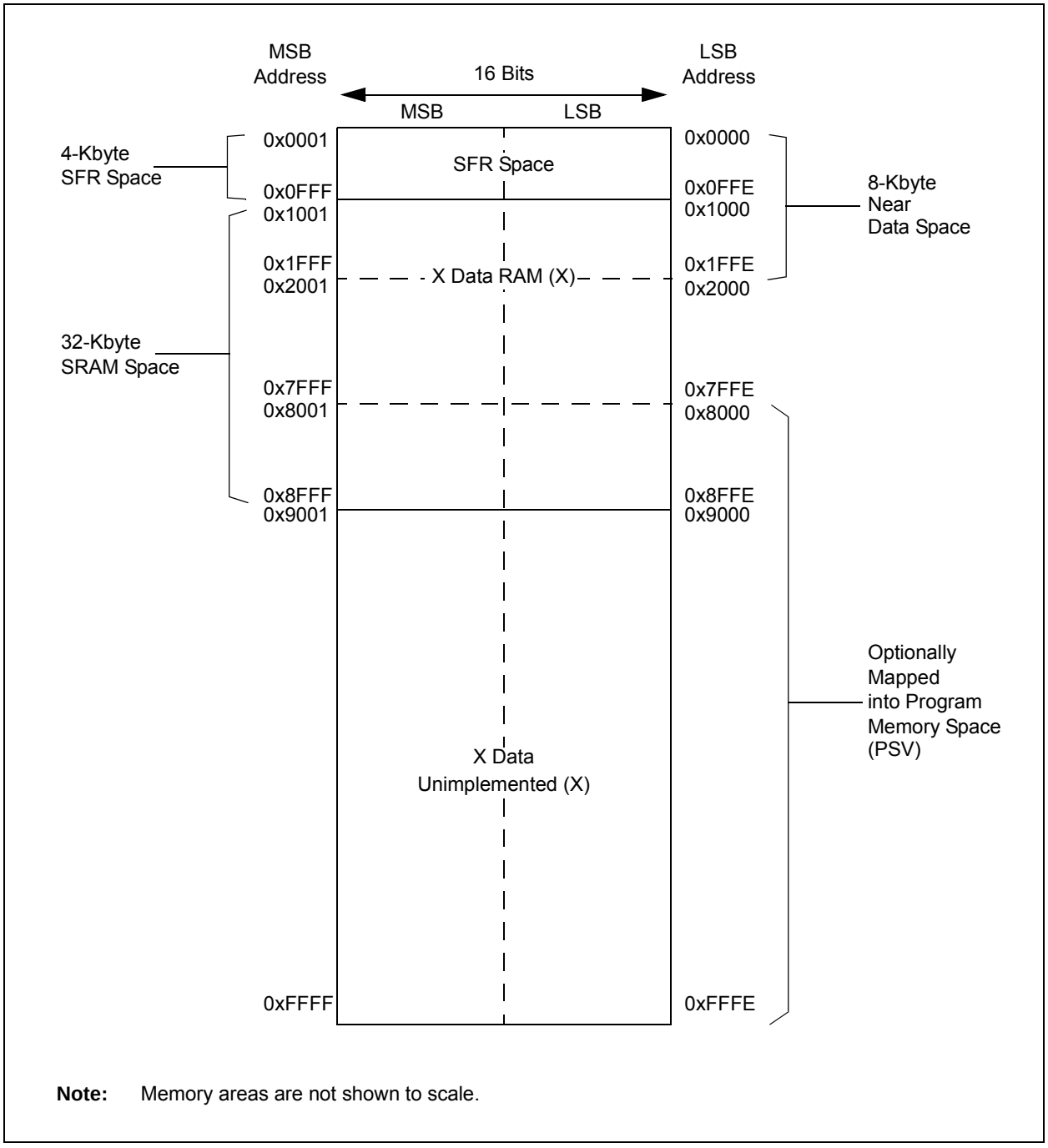
4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

FIGURE 4-12: DATA MEMORY MAP FOR PIC24EP32GP/MC20X/50X DEVICES



Note: Memory areas are not shown to scale.

FIGURE 4-15: DATA MEMORY MAP FOR PIC24EP256GP/MC20X/50X DEVICES



Note: Memory areas are not shown to scale.

4.4.2 EXTENDED X DATA SPACE

The lower portion of the base address space range, between 0x0000 and 0x7FFF, is always accessible regardless of the contents of the Data Space Page registers. It is indirectly addressable through the register indirect instructions. It can be regarded as being located in the default EDS Page 0 (i.e., EDS address range of 0x000000 to 0x007FFF with the base address bit, EA<15> = 0, for this address range). However, Page 0 cannot be accessed through the upper 32 Kbytes, 0x8000 to 0xFFFF, of base Data Space, in combination with DSRPAG = 0x000 or DSWPAG = 0x000. Consequently, DSRPAG and DSWPAG are initialized to 0x001 at Reset.

Note 1: DSxPAG should not be used to access Page 0. An EDS access with DSxPAG set to 0x000 will generate an address error trap.

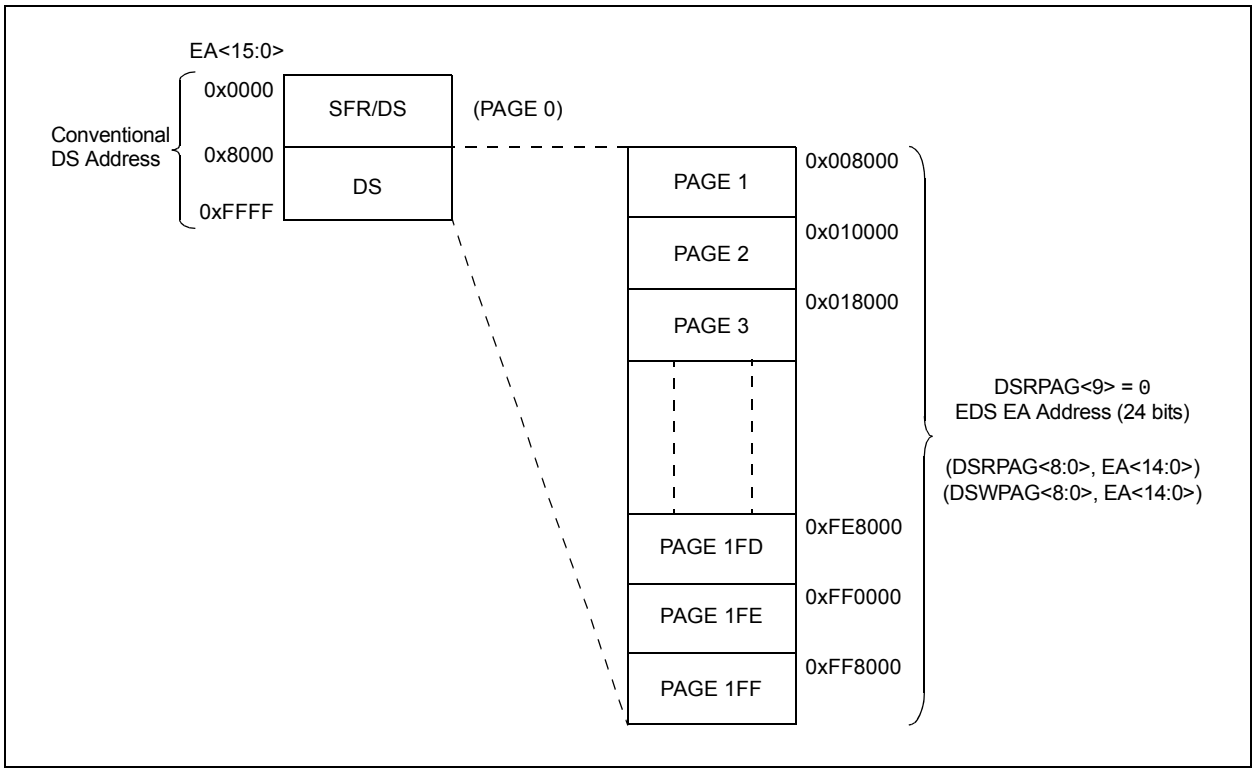
2: Clearing the DSxPAG in software has no effect.

The remaining pages, including both EDS and PSV pages, are only accessible using the DSRPAG or DSWPAG registers in combination with the upper 32 Kbytes, 0x8000 to 0xFFFF, of the base address, where base address bit, EA<15> = 1.

For example, when DSRPAG = 0x001 or DSWPAG = 0x001, accesses to the upper 32 Kbytes, 0x8000 to 0xFFFF, of the Data Space will map to the EDS address range of 0x008000 to 0x00FFFF. When DSRPAG = 0x002 or DSWPAG = 0x002, accesses to the upper 32 Kbytes of the Data Space will map to the EDS address range of 0x010000 to 0x017FFF and so on, as shown in the EDS memory map in Figure 4-17.

For more information on the PSV page access using Data Space Page registers, refer to the **"Program Space Visibility from Data Space"** section in **"Program Memory"** (DS70613) of the *"dsPIC33/PIC24 Family Reference Manual"*.

FIGURE 4-17: EDS MEMORY MAP



11.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORTx, LATx and TRISx registers for data control, port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs other than VDD by using external pull-up resistors. The maximum open-drain voltage allowed on any pin is the same as the maximum VIH specification for that particular pin.

See the **"Pin Diagrams"** section for the available 5V tolerant pins and Table 30-11 for the maximum VIH specification for each pin.

11.2 Configuring Analog and Digital Port Pins

The ANSELx register controls the operation of the analog port pins. The port pins that are to function as analog inputs or outputs must have their corresponding ANSELx and TRISx bits set. In order to use port pins for I/O functionality with digital modules, such as Timers, UARTs, etc., the corresponding ANSELx bit must be cleared.

The ANSELx register has a default value of 0xFFFF; therefore, all pins that share analog functions are analog (not digital) by default.

Pins with analog functions affected by the ANSELx registers are listed with a buffer type of analog in the Pinout I/O Descriptions (see Table 1-1).

If the TRISx bit is cleared (output) while the ANSELx bit is set, the digital output level (VOH or VOL) is converted by an analog peripheral, such as the ADC module or comparator module.

When the PORTx register is read, all pins configured as analog input channels are read as cleared (a low level).

Pins configured as digital inputs do not convert an analog input. Analog levels on any pin defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

11.2.1 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be a NOP, as shown in Example 11-1.

11.3 Input Change Notification (ICN)

The Input Change Notification function of the I/O ports allows devices to generate interrupt requests to the processor in response to a Change-of-State (COS) on selected input pins. This feature can detect input Change-of-States even in Sleep mode, when the clocks are disabled. Every I/O port pin can be selected (enabled) for generating an interrupt request on a Change-of-State.

Three control registers are associated with the Change Notification (CN) functionality of each I/O port. The CNENx registers contain the CN interrupt enable control bits for each of the input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

Each I/O pin also has a weak pull-up and a weak pull-down connected to it. The pull-ups and pull-downs act as a current source or sink source connected to the pin and eliminate the need for external resistors when push button, or keypad devices are connected. The pull-ups and pull-downs are enabled separately, using the CNPUx and the CNPDx registers, which contain the control bits for each of the pins. Setting any of the control bits enables the weak pull-ups and/or pull-downs for the corresponding pins.

Note:	Pull-ups and pull-downs on Change Notification pins should always be disabled when the port pin is configured as a digital output.

EXAMPLE 11-1: PORT WRITE/READ EXAMPLE

```
MOV   0xFF00, W0   ; Configure PORTB<15:8>
                   ; as inputs
MOV   W0, TRISB    ; and PORTB<7:0>
                   ; as outputs
NOP                ; Delay 1 cycle
BTSS  PORTB, #13   ; Next Instruction
```

TABLE 11-1: SELECTABLE INPUT SOURCES (MAPS INPUT TO FUNCTION)

Input Name(1)	Function Name	Register	Configuration Bits
External Interrupt 1	INT1	RPINR0	INT1R<6:0>
External Interrupt 2	INT2	RPINR1	INT2R<6:0>
Timer2 External Clock	T2CK	RPINR3	T2CKR<6:0>
Input Capture 1	IC1	RPINR7	IC1R<6:0>
Input Capture 2	IC2	RPINR7	IC2R<6:0>
Input Capture 3	IC3	RPINR8	IC3R<6:0>
Input Capture 4	IC4	RPINR8	IC4R<6:0>
Output Compare Fault A	OCFA	RPINR11	OCFAR<6:0>
PWM Fault 1(3)	FLT1	RPINR12	FLT1R<6:0>
PWM Fault 2(3)	FLT2	RPINR12	FLT2R<6:0>
QEI1 Phase A(3)	QEA1	RPINR14	QEA1R<6:0>
QEI1 Phase B(3)	QEB1	RPINR14	QEB1R<6:0>
QEI1 Index(3)	INDX1	RPINR15	INDX1R<6:0>
QEI1 Home(3)	HOME1	RPINR15	HOM1R<6:0>
UART1 Receive	U1RX	RPINR18	U1RXR<6:0>
UART2 Receive	U2RX	RPINR19	U2RXR<6:0>
SPI2 Data Input	SDI2	RPINR22	SDI2R<6:0>
SPI2 Clock Input	SCK2	RPINR22	SCK2R<6:0>
SPI2 Slave Select	$\overline{SS2}$	RPINR23	SS2R<6:0>
CAN1 Receive(2)	C1RX	RPINR26	C1RXR<6:0>
PWM Sync Input 1(3)	SYNCI1	RPINR37	SYNCI1R<6:0>
PWM Dead-Time Compensation 1(3)	DTCMP1	RPINR38	DTCMP1R<6:0>
PWM Dead-Time Compensation 2(3)	DTCMP2	RPINR39	DTCMP2R<6:0>
PWM Dead-Time Compensation 3(3)	DTCMP3	RPINR39	DTCMP3R<6:0>

Note 1: Unless otherwise noted, all inputs use the Schmitt Trigger input buffers.

2: This input source is available on dsPIC33EPXXXGP/MC50X devices only.

3: This input source is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

TABLE 11-2: INPUT PIN SELECTION FOR SELECTABLE INPUT SOURCES

Peripheral Pin Select Input Register Value	Input/ Output	Pin Assignment	Peripheral Pin Select Input Register Value	Input/ Output	Pin Assignment
000 0000	I	Vss	010 1101	I	RPI45
000 0001	I	C1OUT(1)	010 1110	I	RPI46
000 0010	I	C2OUT(1)	010 1111	I	RPI47
000 0011	I	C3OUT(1)	011 0000	—	—
000 0100	I	C4OUT(1)	011 0001	—	—
000 0101	—	—	011 0010	—	—
000 0110	I	PTGO30(1)	011 0011	I	RPI51
000 0111	I	PTGO31(1)	011 0100	I	RPI52
000 1000	I	FINDX1(1,2)	011 0101	I	RPI53
000 1001	I	FHOME1(1,2)	011 0110	I/O	RP54
000 1010	—	—	011 0111	I/O	RP55
000 1011	—	—	011 1000	I/O	RP56
000 1100	—	—	011 1001	I/O	RP57
000 1101	—	—	011 1010	I	RPI58
000 1110	—	—	011 1011	—	—
000 1111	—	—	011 1100	—	—
001 0000	—	—	011 1101	—	—
001 0001	—	—	011 1110	—	—
001 0010	—	—	011 1111	—	—
001 0011	—	—	100 0000	—	—
001 0100	I/O	RP20	100 0001	—	—
001 0101	—	—	100 0010	—	—
001 0110	—	—	100 0011	—	—
001 0111	—	—	100 0100	—	—
001 1000	I	RPI24	100 0101	—	—
001 1001	I	RPI25	100 0110	—	—
001 1010	—	—	100 0111	—	—
001 1011	I	RPI27	100 1000	—	—
001 1100	I	RPI28	100 1001	—	—
001 1101	—	—	100 1010	—	—
001 1110	—	—	100 1011	—	—
001 1111	—	—	100 1100	—	—
010 0000	I	RPI32	100 1101	—	—
010 0001	I	RPI33	100 1110	—	—
010 0010	I	RPI34	100 1111	—	—
010 0011	I/O	RP35	101 0000	—	—
010 0100	I/O	RP36	101 0001	—	—
010 0101	I/O	RP37	101 0010	—	—
010 0110	I/O	RP38	101 0011	—	—
010 0111	I/O	RP39	101 0100	—	—

Legend: Shaded rows indicate PPS Input register values that are unimplemented.

Note 1: See **Section 11.4.4.1 “Virtual Connections”** for more information on selecting this pin assignment.

2: These inputs are available on dsPIC33EPXXXGP/MC50X devices only.

REGISTER 19-1: I2CxCON: I2Cx CONTROL REGISTER (CONTINUED)

bit 6 **STREN:** SCLx Clock Stretch Enable bit (when operating as I^2C slave)
Used in conjunction with the SCLREL bit.
1 = Enables software or receives clock stretching
0 = Disables software or receives clock stretching

bit 5 **ACKDT:** Acknowledge Data bit (when operating as I^2C master, applicable during master receive)
Value that is transmitted when the software initiates an Acknowledge sequence.
1 = Sends NACK during Acknowledge
0 = Sends ACK during Acknowledge

bit 4 **ACKEN:** Acknowledge Sequence Enable bit
(when operating as I^2C master, applicable during master receive)
1 = Initiates Acknowledge sequence on SDAx and SCLx pins and transmits ACKDT data bit. Hardware is clear at the end of the master Acknowledge sequence.
0 = Acknowledge sequence is not in progress

bit 3 **RCEN:** Receive Enable bit (when operating as I^2C master)
1 = Enables Receive mode for I^2C. Hardware is clear at the end of the eighth bit of the master receive data byte.
0 = Receive sequence is not in progress

bit 2 **PEN:** Stop Condition Enable bit (when operating as I^2C master)
1 = Initiates Stop condition on SDAx and SCLx pins. Hardware is clear at the end of the master Stop sequence.
0 = Stop condition is not in progress

bit 1 **RSEN:** Repeated Start Condition Enable bit (when operating as I^2C master)
1 = Initiates Repeated Start condition on SDAx and SCLx pins. Hardware is clear at the end of the master Repeated Start sequence.
0 = Repeated Start condition is not in progress

bit 0 **SEN:** Start Condition Enable bit (when operating as I^2C master)
1 = Initiates Start condition on SDAx and SCLx pins. Hardware is clear at the end of the master Start sequence.
0 = Start condition is not in progress

Note 1: When performing master operations, ensure that the IPMIEN bit is set to '0'.

REGISTER 21-11: CxFEN1: ECANx ACCEPTANCE FILTER ENABLE REGISTER 1

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
FLTEN15	FLTEN14	FLTEN13	FLTEN12	FLTEN11	FLTEN10	FLTEN9	FLTEN8
bit 15							bit 8

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
FLTEN7	FLTEN6	FLTEN5	FLTEN4	FLTEN3	FLTEN2	FLTEN1	FLTEN0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **FLTEN<15:0>:** Enable Filter n to Accept Messages bits
1 = Enables Filter n
0 = Disables Filter n

REGISTER 21-12: CxBUFPNT1: ECANx FILTER 0-3 BUFFER POINTER REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F3BP<3:0>				F2BP<3:0>			
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F1BP<3:0>				F0BP<3:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **F3BP<3:0>:** RX Buffer Mask for Filter 3 bits
1111 = Filter hits received in RX FIFO buffer
1110 = Filter hits received in RX Buffer 14
•
•
•
0001 = Filter hits received in RX Buffer 1
0000 = Filter hits received in RX Buffer 0

bit 11-8 **F2BP<3:0>:** RX Buffer Mask for Filter 2 bits (same values as bits<15:12>)

bit 7-4 **F1BP<3:0>:** RX Buffer Mask for Filter 1 bits (same values as bits<15:12>)

bit 3-0 **F0BP<3:0>:** RX Buffer Mask for Filter 0 bits (same values as bits<15:12>)

22.0 CHARGE TIME MEASUREMENT UNIT (CTMU)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Charge Time Measurement Unit (CTMU)"** (DS70661) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available on the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Charge Time Measurement Unit is a flexible analog module that provides accurate differential time measurement between pulse sources, as well as asynchronous pulse generation. Its key features include:

- Four Edge Input Trigger Sources
- Polarity Control for Each Edge Source
- Control of Edge Sequence
- Control of Response to Edges
- Precise Time Measurement Resolution of 1 ns
- Accurate Current Source Suitable for Capacitive Measurement
- On-Chip Temperature Measurement using a Built-in Diode

Together with other on-chip analog modules, the CTMU can be used to precisely measure time, measure capacitance, measure relative changes in capacitance or generate output pulses that are independent of the system clock.

The CTMU module is ideal for interfacing with capacitive-based sensors.The CTMU is controlled through three registers: CTMUCON1, CTMUCON2 and CTMUICON. CTMUCON1 and CTMUCON2 enable the module and control edge source selection, edge source polarity selection and edge sequencing. The CTMUICON register controls the selection and trim of the current source.

TABLE 24-1: PTG STEP COMMAND FORMAT (CONTINUED)

bit 3-0	Step Command	OPTION<3:0>	Option Description
	PTGWHI(1) or PTGWLO(1)	0000	PWM Special Event Trigger.(3)
		0001	PWM master time base synchronization output.(3)
		0010	PWM1 interrupt.(3)
		0011	PWM2 interrupt.(3)
		0100	PWM3 interrupt.(3)
		0101	Reserved.
		0110	Reserved.
		0111	OC1 Trigger event.
		1000	OC2 Trigger event.
		1001	IC1 Trigger event.
		1010	CMP1 Trigger event.
		1011	CMP2 Trigger event.
		1100	CMP3 Trigger event.
		1101	CMP4 Trigger event.
		1110	ADC conversion done interrupt.
		1111	INT2 external interrupt.
	PTGIRQ(1)	0000	Generate PTG Interrupt 0.
		0001	Generate PTG Interrupt 1.
		0010	Generate PTG Interrupt 2.
		0011	Generate PTG Interrupt 3.
		0100	Reserved.
		• • •	• • •
		1111	Reserved.
	PTGTRIG(2)	00000	PTGO0.
		00001	PTGO1.
		• • •	• • •
		11110	PTGO30.
		11111	PTGO31.

Note 1: All reserved commands or options will execute but have no effect (i.e., execute as a NOP instruction).

2: Refer to Table 24-2 for the trigger output descriptions.

3: This feature is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

REGISTER 25-1: CMSTAT: OP AMP/COMPARATOR STATUS REGISTER (CONTINUED)

bit 1 **C2OUT:** Comparator 2 Output Status bit(2)

When CPOL = 0:
1 = VIN+ > VIN-
0 = VIN+ < VIN-

When CPOL = 1:
1 = VIN+ < VIN-
0 = VIN+ > VIN-

bit 0 **C1OUT:** Comparator 1 Output Status bit(2)

When CPOL = 0:
1 = VIN+ > VIN-
0 = VIN+ < VIN-

When CPOL = 1:
1 = VIN+ < VIN-
0 = VIN+ > VIN-

Note 1: Reflects the value of the of the CEVT bit in the respective Op Amp/Comparator Control register, CMxCON<9>.

2: Reflects the value of the COUT bit in the respective Op Amp/Comparator Control register, CMxCON<8>.

TABLE 27-2: CONFIGURATION BITS DESCRIPTION

Bit Field	Description
GCP	General Segment Code-Protect bit 1 = User program memory is not code-protected 0 = Code protection is enabled for the entire program memory space
GWRP	General Segment Write-Protect bit 1 = User program memory is not write-protected 0 = User program memory is write-protected
IESO	Two-Speed Oscillator Start-up Enable bit 1 = Start up device with FRC, then automatically switch to the user-selected oscillator source when ready 0 = Start up device with user-selected oscillator source
PWMLOCK(1)	PWM Lock Enable bit 1 = Certain PWM registers may only be written after a key sequence 0 = PWM registers may be written without a key sequence
FNOSC<2:0>	Oscillator Selection bits 111 = Fast RC Oscillator with Divide-by-N (FRCDIVN) 110 = Fast RC Oscillator with Divide-by-16 (FRCDIV16) 101 = Low-Power RC Oscillator (LPRC) 100 = Reserved; do not use 011 = Primary Oscillator with PLL module (XT + PLL, HS + PLL, EC + PLL) 010 = Primary Oscillator (XT, HS, EC) 001 = Fast RC Oscillator with Divide-by-N with PLL module (FRCPLL) 000 = Fast RC Oscillator (FRC)
FCKSM<1:0>	Clock Switching Mode bits 1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled 01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled 00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled
IOL1WAY	Peripheral Pin Select Configuration bit 1 = Allow only one reconfiguration 0 = Allow multiple reconfigurations
OSCIOFNC	OSC2 Pin Function bit (except in XT and HS modes) 1 = OSC2 is the clock output 0 = OSC2 is a general purpose digital I/O pin
POSCMD<1:0>	Primary Oscillator Mode Select bits 11 = Primary Oscillator is disabled 10 = HS Crystal Oscillator mode 01 = XT Crystal Oscillator mode 00 = EC (External Clock) mode
FWDTEN	Watchdog Timer Enable bit 1 = Watchdog Timer is always enabled (LPRC oscillator cannot be disabled. Clearing the SWDTEN bit in the RCON register will have no effect.) 0 = Watchdog Timer is enabled/disabled by user software (LPRC can be disabled by clearing the SWDTEN bit in the RCON register)
WINDIS	Watchdog Timer Window Enable bit 1 = Watchdog Timer in Non-Window mode 0 = Watchdog Timer in Window mode
PLLKEN	PLL Lock Enable bit 1 = PLL lock is enabled 0 = PLL lock is disabled

Note 1: This bit is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

2: When JTAGEN = 1, an internal pull-up resistor is enabled on the TMS pin. Erased devices default to JTAGEN = 1. Applications requiring I/O pins in a high-impedance state (tri-state) in Reset should use pins other than TMS for this purpose.

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
	IIL	**Input Leakage Current(1,2)**					
DI50		I/O Pins 5V Tolerant(3)	-1	—	+1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +85°C
DI51a		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +85°C
DI51b		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +125°C
DI51c		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +125°C
DI55		$\overline{\text{MCLR}}$	-5	—	+5	μA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	-5	—	+5	μA	VSS ≤ VPIN ≤ VDD, XT and HS modes

Note 1: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: See the **"Pin Diagrams"** section for the 5V tolerant I/O pins.

4: VIL source < (VSS – 0.3). Characterized but not tested.

5: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

8: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

FIGURE 30-12: QEA/QEB INPUT CHARACTERISTICS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

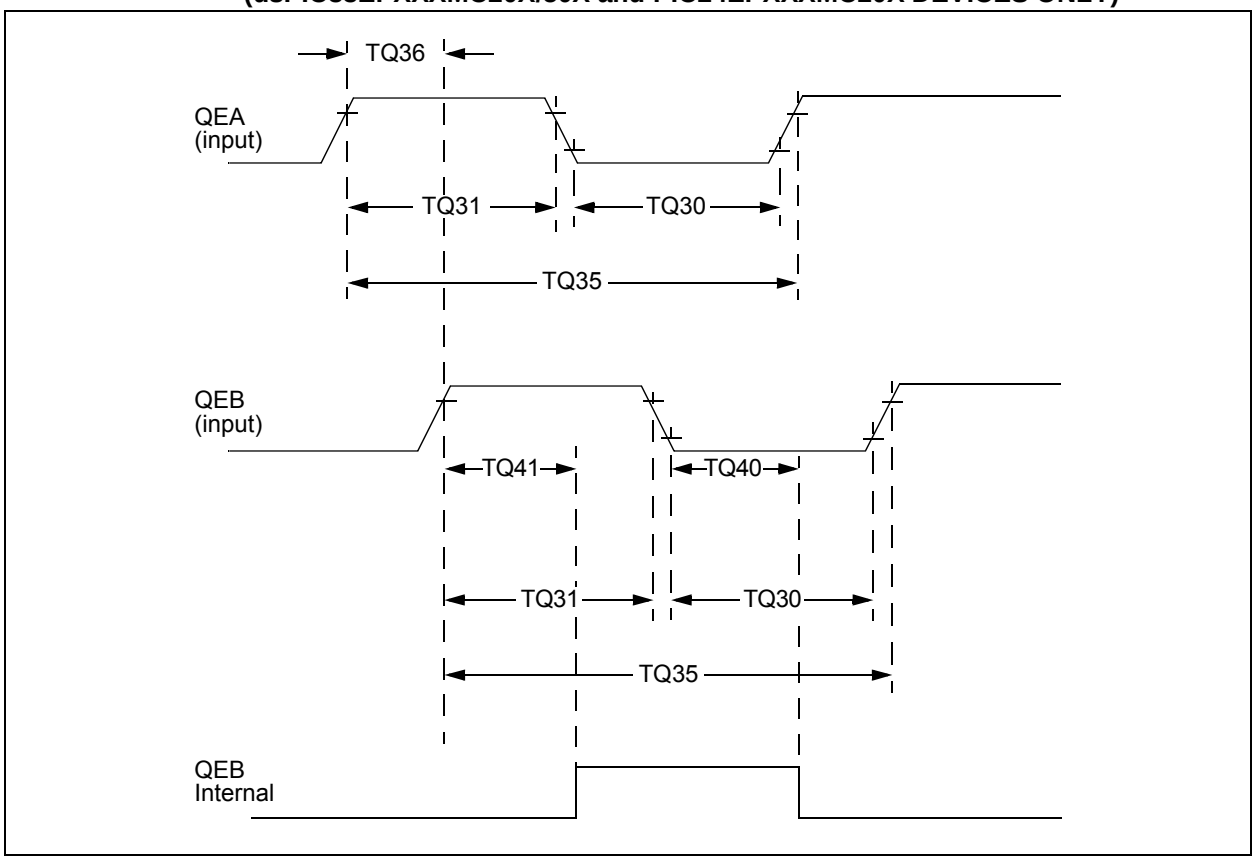


TABLE 30-31: QUADRATURE DECODER TIMING REQUIREMENTS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic(1)**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
TQ30	TQUL	Quadrature Input Low Time	6 TCY	—	ns	
TQ31	TQUH	Quadrature Input High Time	6 TCY	—	ns	
TQ35	TQUIN	Quadrature Input Period	12 TCY	—	ns	
TQ36	TQUP	Quadrature Phase Period	3 TCY	—	ns	
TQ40	TQUFL	Filter Time to Recognize Low, with Digital Filter	3 * N * TCY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 **(Note 3)**
TQ41	TQUFH	Filter Time to Recognize High, with Digital Filter	3 * N * TCY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 **(Note 3)**

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: N = Index Channel Digital Filter Clock Divide Select bits. Refer to **"Quadrature Encoder Interface (QEI)"** (DS70601) in the "*dsPIC33/PIC24 Family Reference Manual*". Please see the Microchip web site for the latest family reference manual sections.

FIGURE 30-21: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS

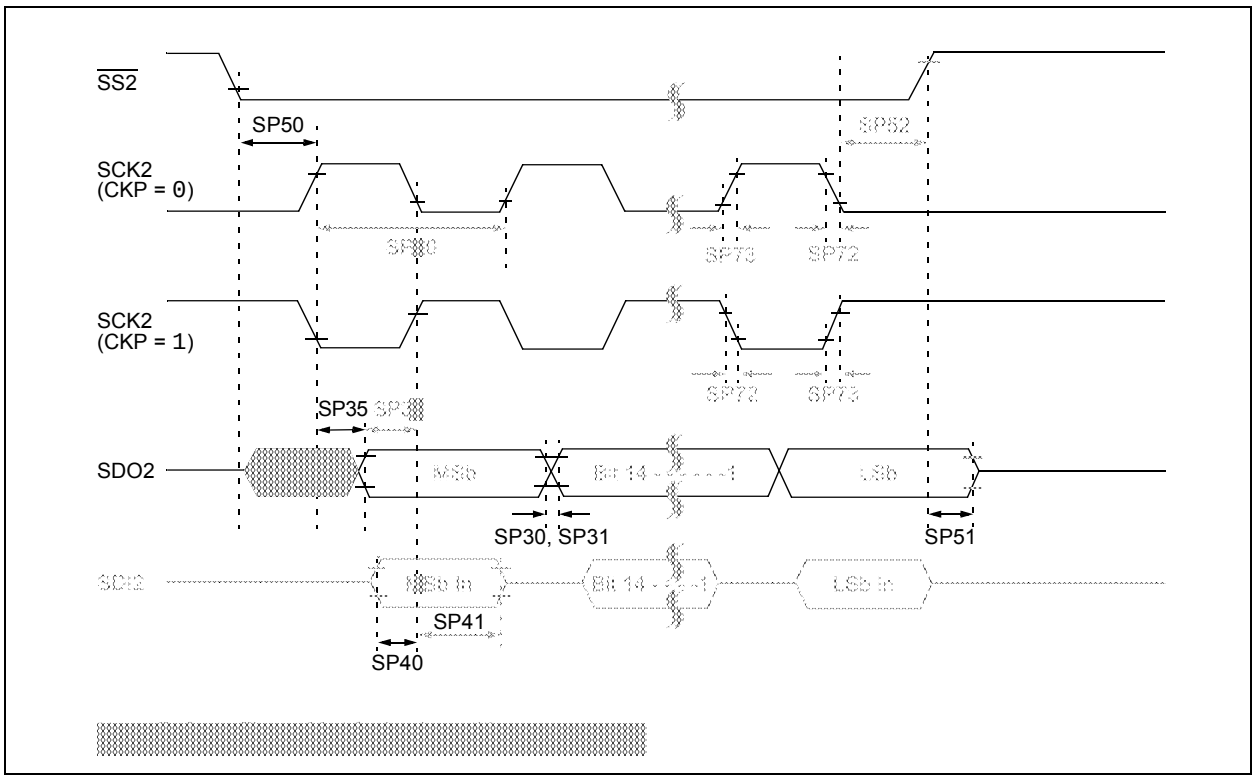


TABLE 30-40: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	11	MHz	**(Note 3)**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS2}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS2}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{SS2}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

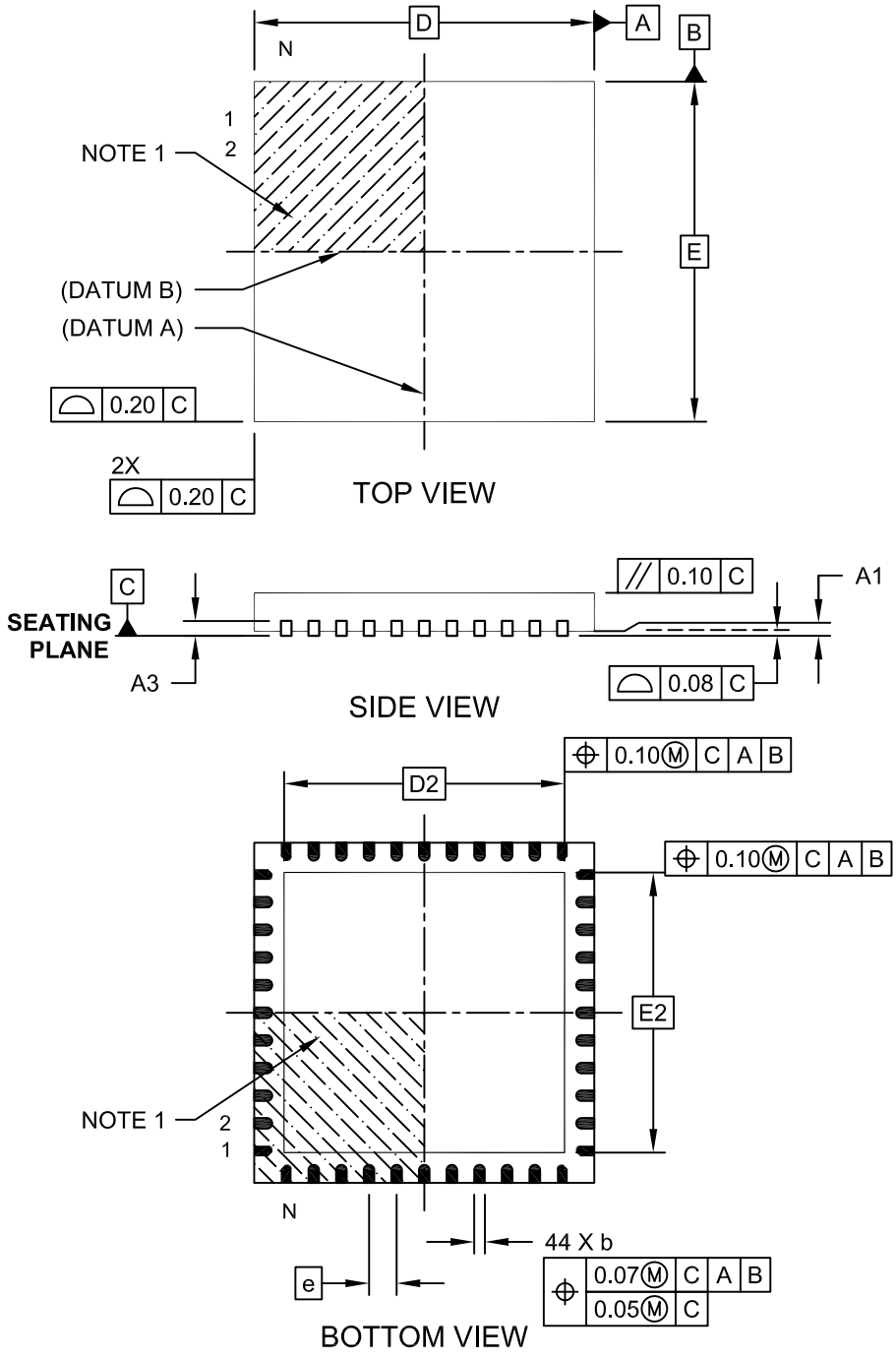
2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 91 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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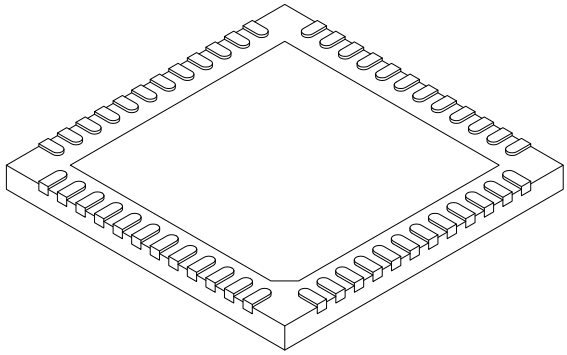
48-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 6x6x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		48	
Pitch	e		0.40 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.127 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	4.45	4.60	4.75
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	4.45	4.60	4.75
Contact Width	b	0.15	0.20	0.25
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-153A Sheet 2 of 2